ASSOCIATION CONNECTING LECTRONICS INDUSTRIES INDUSTRIES	C. Bannockh	urn. Illinois. A	Il rights reserved u ntions.	nder both	This docum level parts, t	ent is a declara	tion of the encompass	substance es all low	s within the manufacture vertices within the manufacture of the second sec	urer listed which the	item. Note: i manufacture	if the item is an as r has engineering	sembly with lower responsibility.	
	P-21.1 IPC Web Site for Information on IPC-1752 Standard For http://www.ipc.org/IPC-175x Dis								rials and N	als and Mfg Information				
Supplier Information														
Company name*	Company unique ID			Unique ID Authority					Response Date*					
onsemi										2024-0	2024-05-21			
Contact Name Title - Con			e - Contact			Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - R			tle - Representative			Phone - Representative*			Email	Email - Representative*				
Product-Env-Stewards Product En			duct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item Num		Jumber Mfr Item Name			Effective Dat	e Versio	ı	Manufacturing Site		Weight*	UOM	Unit Type	
	MC10EP	451FAG	BBG ECL FLIP FLOP RESET			2024-05-21			PH1		175.1	mg	Each	
Manufacturing Proccess Informati	on		·										·	
Terminal Plating / Grid Array Mate	Terminal Plating / Grid Array Material Terminal Base		Alloy J	J-STD-020 MSI	L Rating	Peak Pro	cess Body	Temperat	ure Max Time at Peal	k Tempera	ature Numl	ber of Reflow Cy	les	
Matte Tin (Sn) - annealed CU Alloy		2	2		260		С	30	seco	nds 3				
Comments														
ATTENTION: MSL 2 Rated item requires	Dry Pack (a	fter electrical	test)											
For more information regarding material c	omposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl ate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.33	mg	Supplier	Silicon (Si)	7440-21-3		0.33	mg
Die Attach	3.19	mg	Supplier	Silver (Ag)	7440-22-4		2.3925	mg
			Supplier	Epoxy resins	129915-35-1		0.7975	mg
Lead Frame 49	49.99	mg	Supplier	Silver (Ag)	7440-22-4		0.15	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.05	mg
			Supplier	Silicon (Si)	7440-21-3		0.3499	mg
			В	Nickel (Ni)	7440-02-0		1.4997	mg
			Supplier	Copper (Cu)	7440-50-8		47.9404	mg
Mold Compound-Black	114.24	mg		Epoxy Phenol Resin	proprietary data		11.9952	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		102.2448	mg
Plating	6.7	mg	Supplier	Tin (Sn)	7440-31-5		6.7	mg
Wire Bond - Au	0.65	mg	Supplier	Gold (Au)	7440-57-5		0.65	mg